

**Final Product Change Notification**

202003004F01

**Issue Date:** 10-Apr-2020

**Effective Date:** 24-Jul-2020

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia. For detailed information we invite you to view this notification online



**Change Category**

- |                                                         |                                                        |                                                    |                                         |                                                         |
|---------------------------------------------------------|--------------------------------------------------------|----------------------------------------------------|-----------------------------------------|---------------------------------------------------------|
| <input checked="" type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input checked="" type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location             | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

**Assembly site transfer of SOT363 (SC-88) package**

**Details of this Change**

Nexperia assembly site transfer of SOT363 (SC-88) package from ATSN (assembly and test center Seremban Malaysia) to ATGD (assembly and test center Guangdong China).

The assembly site transfer is combined with the introduction of a new epoxy mould compound (CEL-1700HF). Additionally for one product type, 8 inch wafer diameter will be released and the bond wire material will be changed from gold (Au) to copper (Cu).

Following the details:

**Current products**

- assembly site ATSN
- epoxy mould compound: GR646 (Henkel), 3400FPG (Panasonic) or EME-E500HK (Sumitomo).
- 6 inch (where affected)
- Au wire (where affected)

**Changed products:**

- assembly site ATGD
- epoxy mould compound: CEL-1700HF (Hitachi)
- 6 or 8 inch (where affected)
- Cu wire (where affected)

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

**Why do we implement this Change**

- to achieve a higher and flexible supply capability.
- improved epoxy mould compound adhesive
- to increase flexibility and volume ramp-up.

- aligning with world technology standards, Nexperia continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

#### **Identification of Affected Products**

Changed products will be identified by the assembly identifier on the marking and label and the date code after implementation.

### **Product Availability**

#### **Sample Information**

Samples are available upon request

Latest sample request date for PCN samples is 10-May-2020.

#### **Production**

Planned first shipment 24-Jul-2020

### **Impact**

No impact to the products' functionality anticipated.

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 10-May-2020. Lack of acknowledgement of the PCN constitutes acceptance of the change.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

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**Affected OPN****Affected 12NC**

BAS16VY,165	934057343165
BAS16VY,115	934057343115
BAT54XY,115	934059127115
BAS40XY,115	934059955115
BAV99S,115	934056610115
BAT754L,115	934056331115
BAT54XYH	934059127125
BAS70XY,115	934059956115
BAV99S,135	934056610135